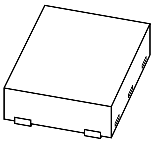


# PBSS4330PA

## 30 V, 3 A NPN low $V_{CEsat}$ (BISS) transistor

Rev. 01 — 19 April 2010 Product data sheet

## 1. Product profile

### 1.1 General description

NPN low $V_{CEsat}$ Breakthrough In Small Signal (BISS) transistor, encapsulated in an ultra thin SOT1061 leadless small Surface-Mounted Device (SMD) plastic package with medium power capability.

PNP complement: PBSS5330PA.

### 1.2 Features and benefits

- Low collector-emitter saturation voltage $V_{CEsat}$
- High collector current capability $I_C$ and $I_{CM}$
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors
- Exposed heat sink for excellent thermal and electrical conductivity
- Leadless small SMD plastic package with medium power capability

### 1.3 Applications

- Loadswitch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

### 1.4 Quick reference data

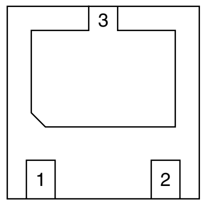
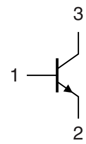
**Table 1. Quick reference data**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_{CEO}$ | collector-emitter voltage | open base | | - | - | 30 | V |
| $I_C$ | collector current | | | - | - | 3 | A |
| $I_{CM}$ | peak collector current | single pulse; $t_p \leq 1$ ms | | - | - | 5 | A |
| $R_{CEsat}$ | collector-emitter saturation resistance | $I_C = 3$ A; $I_B = 300$ mA | [1] | - | 75 | 100 | mΩ |

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$.

## 2. Pinning information

**Table 2. Pinning**

| Pin | Description | Simplified outline | Graphic symbol |
|---|---|---|---|
| 1 | base |  Transparent top view |  sym021 |
| 2 | emitter | | |
| 3 | collector | | |

## 3. Ordering information

**Table 3. Ordering information**

| Type number | Package | | |
|---|---|---|---|
| | Name | Description | Version |
| PBSS4330PA | HUSON3 | plastic thermal enhanced ultra thin small outline package; no leads; three terminals; body 2 × 2 × 0.65 mm | SOT1061 |

## 4. Marking

**Table 4. Marking codes**

| Type number | Marking code |
|---|---|
| PBSS4330PA | AH |

## 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{CBO}$ | collector-base voltage | open emitter | | - | 50 | V |
| $V_{CEO}$ | collector-emitter voltage | open base | | - | 30 | V |
| $V_{EBO}$ | emitter-base voltage | open collector | | - | 6 | V |
| $I_C$ | collector current | | | - | 3 | A |
| $I_{CM}$ | peak collector current | single pulse; $t_p \leq 1$ ms | | - | 5 | A |
| $I_B$ | base current | | | - | 500 | mA |
| $P_{tot}$ | total power dissipation | $T_{amb} \leq 25$ °C | [1] | - | 500 | mW |
| | | | [2] | - | 1 | W |
| | | | [3] | - | 1.25 | W |
| | | | [4] | - | 2.1 | W |

**Table 5. Limiting values** *...continued*

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

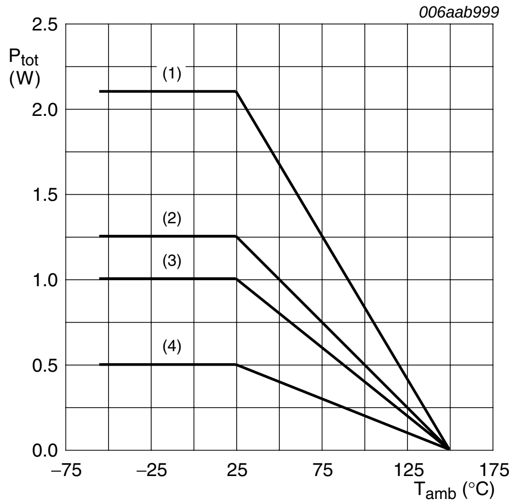
| Symbol | Parameter | Conditions | Min | Max | Unit |
|---|---|---|---|---|---|
| $T_j$ | junction temperature | | - | 150 | °C |
| $T_{amb}$ | ambient temperature | | –55 | +150 | °C |
| $T_{stg}$ | storage temperature | | –65 | +150 | °C |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 $cm^2$.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 $cm^2$.

[4] Device mounted on a ceramic PCB, $Al_2O_3$, standard footprint.




(1) Ceramic PCB, $Al_2O_3$, standard footprint

(2) FR4 PCB, mounting pad for collector 6 $cm^2$

(3) FR4 PCB, mounting pad for collector 1 $cm^2$

(4) FR4 PCB, standard footprint

**Fig 1. Power derating curves**

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

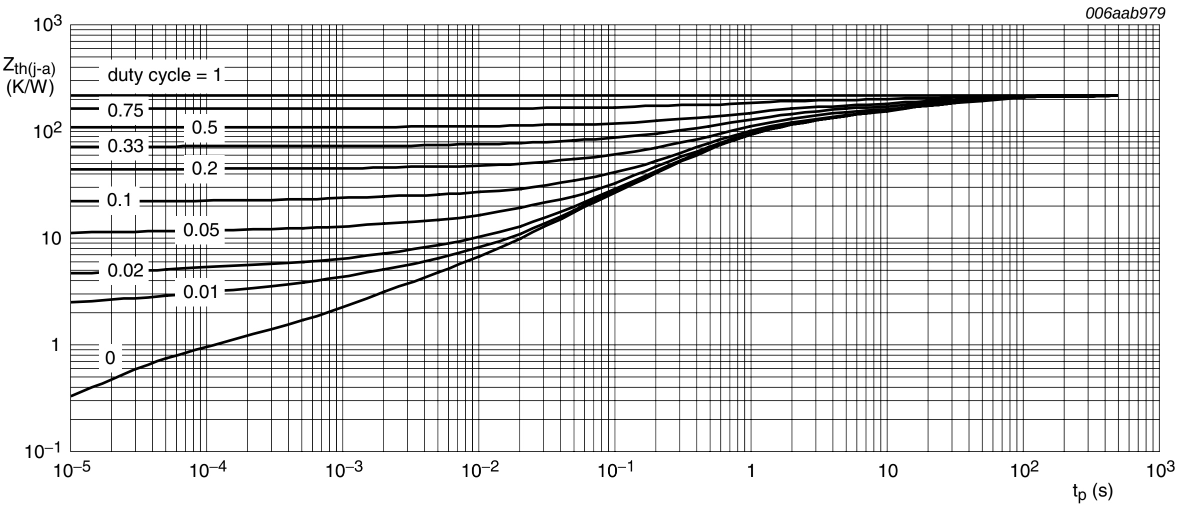
| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | - | 250 | K/W |
| | | | [2] | - | - | 125 | K/W |
| | | | [3] | - | - | 100 | K/W |
| | | | [4] | - | - | 60 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 $cm^2$.

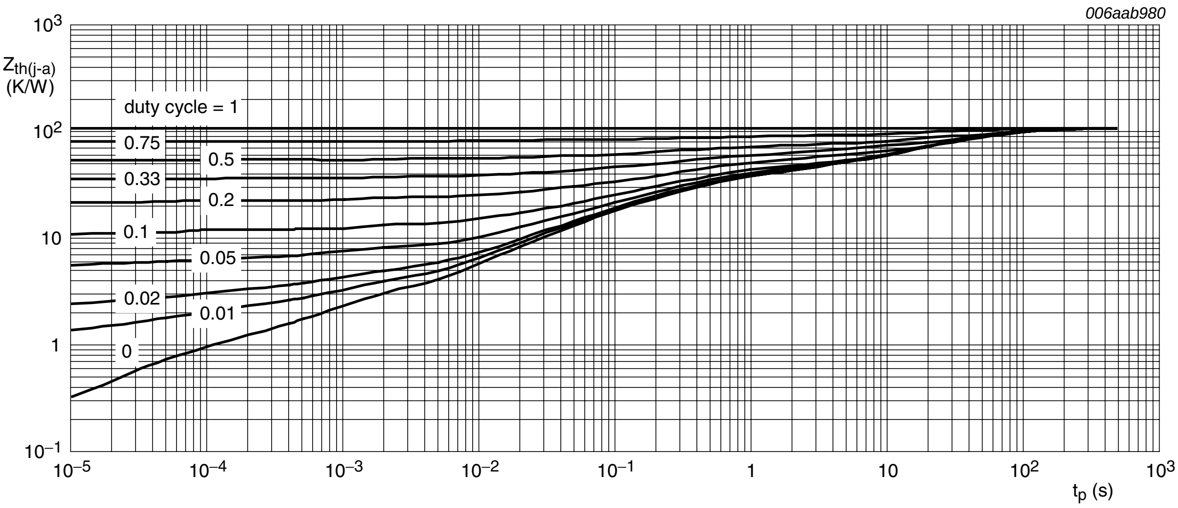
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 $cm^2$.

[4] Device mounted on a ceramic PCB, $Al_2O_3$, standard footprint.



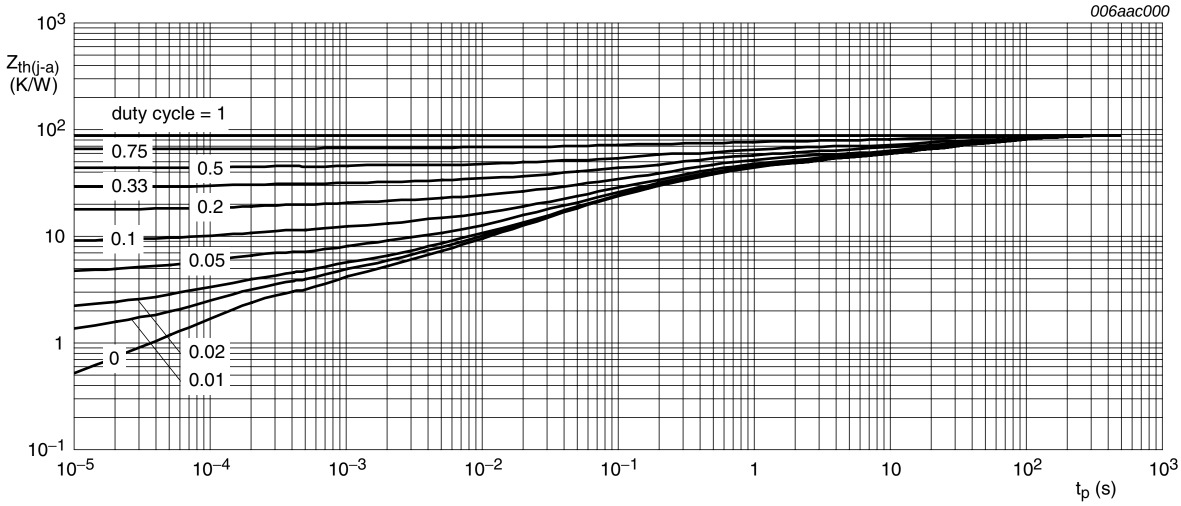

FR4 PCB, standard footprint

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



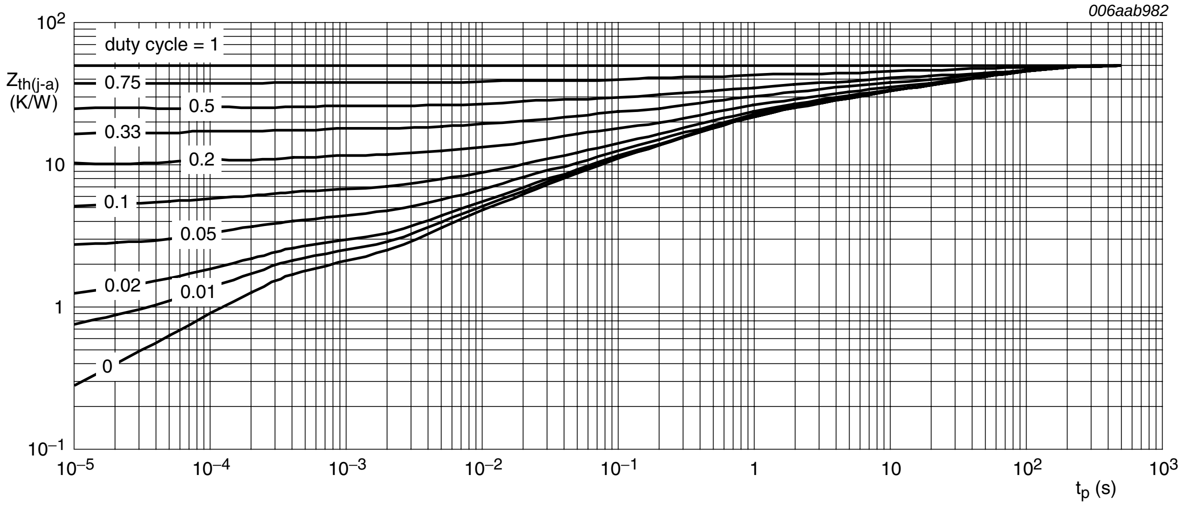

FR4 PCB, mounting pad for collector 1 $cm^2$

**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**




FR4 PCB, mounting pad for collector 6 $cm^2$

**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**




Ceramic PCB, $Al_2O_3$, standard footprint

**Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

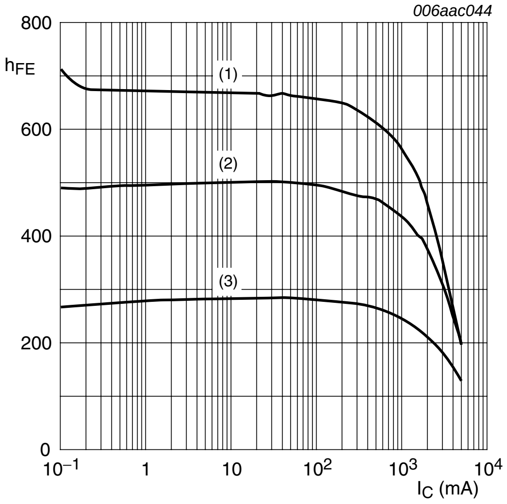
# 7. Characteristics

**Table 7. Characteristics**

*$T_{amb}$ = 25 °C unless otherwise specified.*

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $I_{CBO}$ | collector-base cut-off current | $V_{CB}$ = 30 V; $I_E$ = 0 A | | - | - | 100 | nA |
| | | $V_{CB}$ = 30 V; $I_E$ = 0 A; $T_j$ = 150 °C | | - | - | 50 | µA |
| $I_{CES}$ | collector-emitter cut-off current | $V_{CE}$ = 30 V; $V_{BE}$ = 0 V | | - | - | 100 | nA |
| $I_{EBO}$ | emitter-base cut-off current | $V_{EB}$ = 5 V; $I_C$ = 0 A | | - | - | 100 | nA |
| $h_{FE}$ | DC current gain | $V_{CE}$ = 2 V | [1] | | | | |
| | | $I_C$ = 0.5 A | | 300 | 465 | - | |
| | | $I_C$ = 1 A | | 270 | 435 | 700 | |
| | | $I_C$ = 2 A | | 230 | 370 | - | |
| | | $I_C$ = 3 A | | 180 | 310 | - | |
| $V_{CEsat}$ | collector-emitter saturation voltage | $I_C$ = 0.5 A; $I_B$ = 50 mA | [1] | - | 40 | 60 | mV |
| | | $I_C$ = 1 A; $I_B$ = 50 mA | [1] | - | 80 | 110 | mV |
| | | $I_C$ = 2 A; $I_B$ = 100 mA | [1] | - | 155 | 220 | mV |
| | | $I_C$ = 3 A; $I_B$ = 300 mA | [1] | - | 220 | 300 | mV |
| $R_{CEsat}$ | collector-emitter saturation resistance | $I_C$ = 3 A; $I_B$ = 300 mA | [1] | - | 75 | 100 | mΩ |
| $V_{BEsat}$ | base-emitter saturation voltage | $I_C$ = 2 A; $I_B$ = 100 mA | [1] | - | 0.95 | 1.1 | V |
| | | $I_C$ = 3 A; $I_B$ = 300 mA | [1] | - | 1.07 | 1.2 | V |
| $V_{BEon}$ | base-emitter turn-on voltage | $V_{CE}$ = 2 V; $I_C$ = 1 A | [1] | - | 0.76 | 1 | V |
| $t_d$ | delay time | $V_{CC}$ = 9 V; $I_C$ = 2 A; $I_{Bon}$ = 0.1 A; $I_{Boff}$ = −0.1 A | | - | 11 | - | ns |
| $t_r$ | rise time | | | - | 52 | - | ns |
| $t_{on}$ | turn-on time | | | - | 63 | - | ns |
| $t_s$ | storage time | | | - | 230 | - | ns |
| $t_f$ | fall time | | | - | 40 | - | ns |
| $t_{off}$ | turn-off time | | | - | 270 | - | ns |
| $f_T$ | transition frequency | $V_{CE}$ = 5 V; $I_C$ = 100 mA; f = 100 MHz | | 100 | 210 | - | MHz |
| $C_c$ | collector capacitance | $V_{CB}$ = 10 V; $I_E$ = $i_e$ = 0 A; f = 1 MHz | | - | 21 | 30 | pF |

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$.



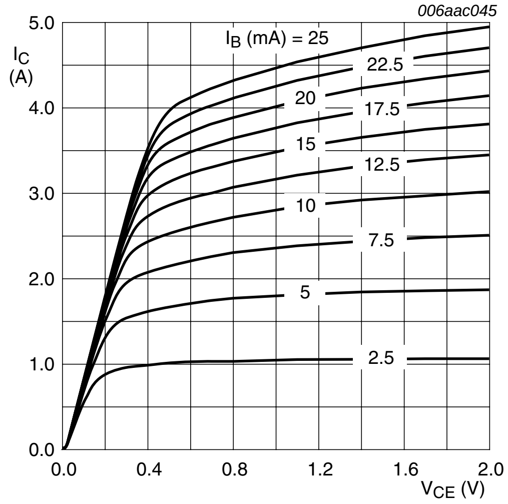

$V_{CE}$ = 2 V

(1) $T_{amb}$ = 100 °C

(2) $T_{amb}$ = 25 °C

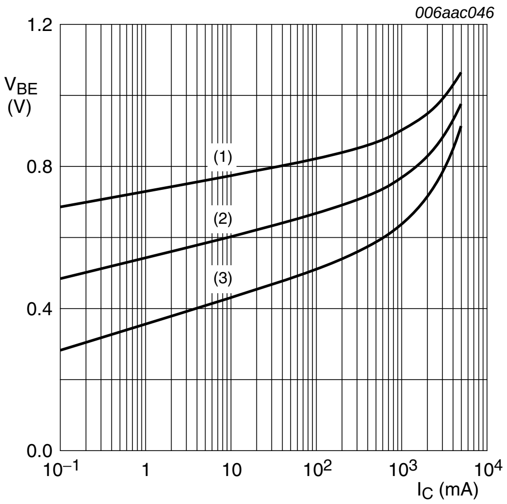
(3) $T_{amb}$ = −55 °C

**Fig 6. DC current gain as a function of collector current; typical values**




$T_{amb}$ = 25 °C

**Fig 7. Collector current as a function of collector-emitter voltage; typical values**



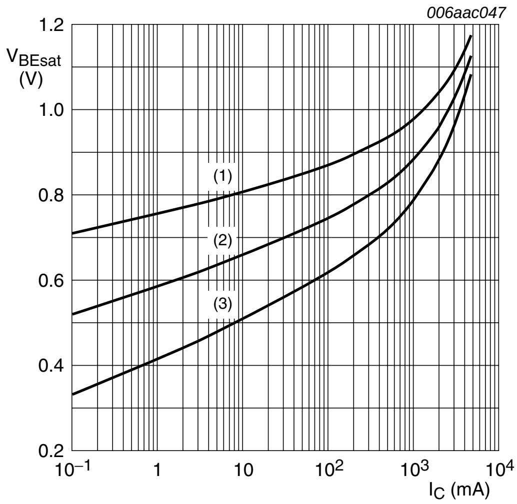

$V_{CE}$ = 2 V

(1) $T_{amb}$ = −55 °C

(2) $T_{amb}$ = 25 °C

(3) $T_{amb}$ = 100 °C

**Fig 8. Base-emitter voltage as a function of collector current; typical values**



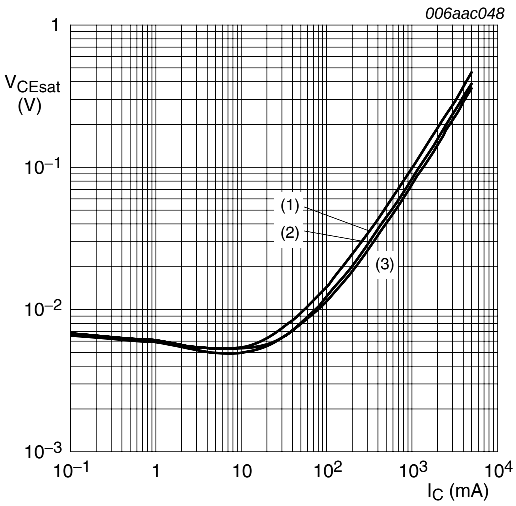

$I_C/I_B$ = 20

(1) $T_{amb}$ = −55 °C

(2) $T_{amb}$ = 25 °C

(3) $T_{amb}$ = 100 °C

**Fig 9. Base-emitter saturation voltage as a function of collector current; typical values**



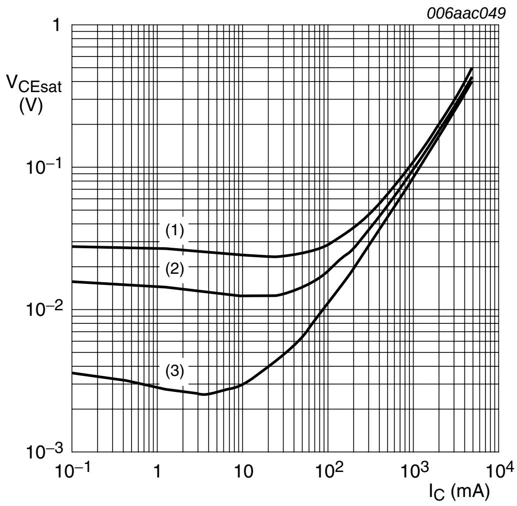

$I_C/I_B = 20$

(1) $T_{amb} = 100\ °C$

(2) $T_{amb} = 25\ °C$

(3) $T_{amb} = -55\ °C$

**Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values**



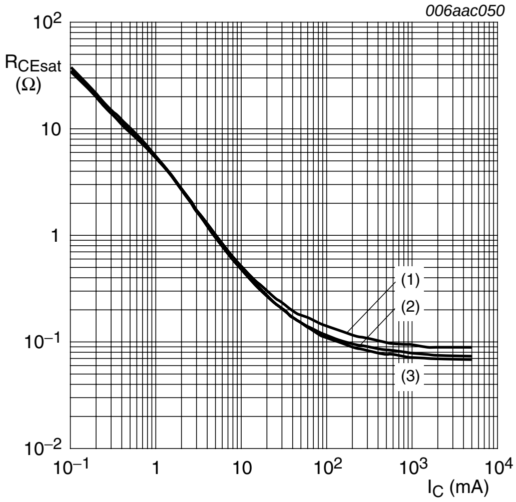

$T_{amb} = 25\ °C$

(1) $I_C/I_B = 100$

(2) $I_C/I_B = 50$

(3) $I_C/I_B = 10$

**Fig 11. Collector-emitter saturation voltage as a function of collector current; typical values**



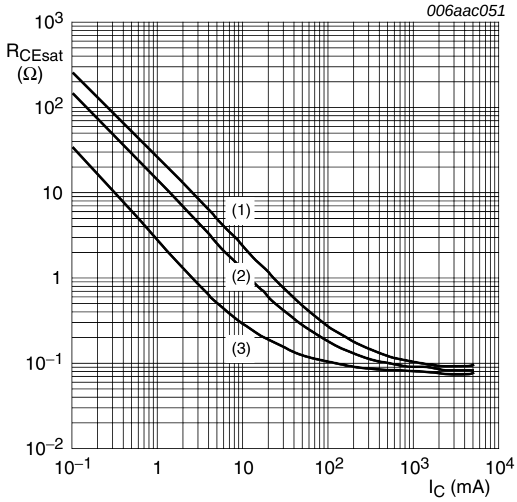

$I_C/I_B = 20$

(1) $T_{amb} = 100\ °C$

(2) $T_{amb} = 25\ °C$

(3) $T_{amb} = -55\ °C$

**Fig 12. Collector-emitter saturation resistance as a function of collector current; typical values**




$T_{amb} = 25\ °C$

(1) $I_C/I_B = 100$

(2) $I_C/I_B = 50$

(3) $I_C/I_B = 10$

**Fig 13. Collector-emitter saturation resistance as a function of collector current; typical values**

# 8. Test information

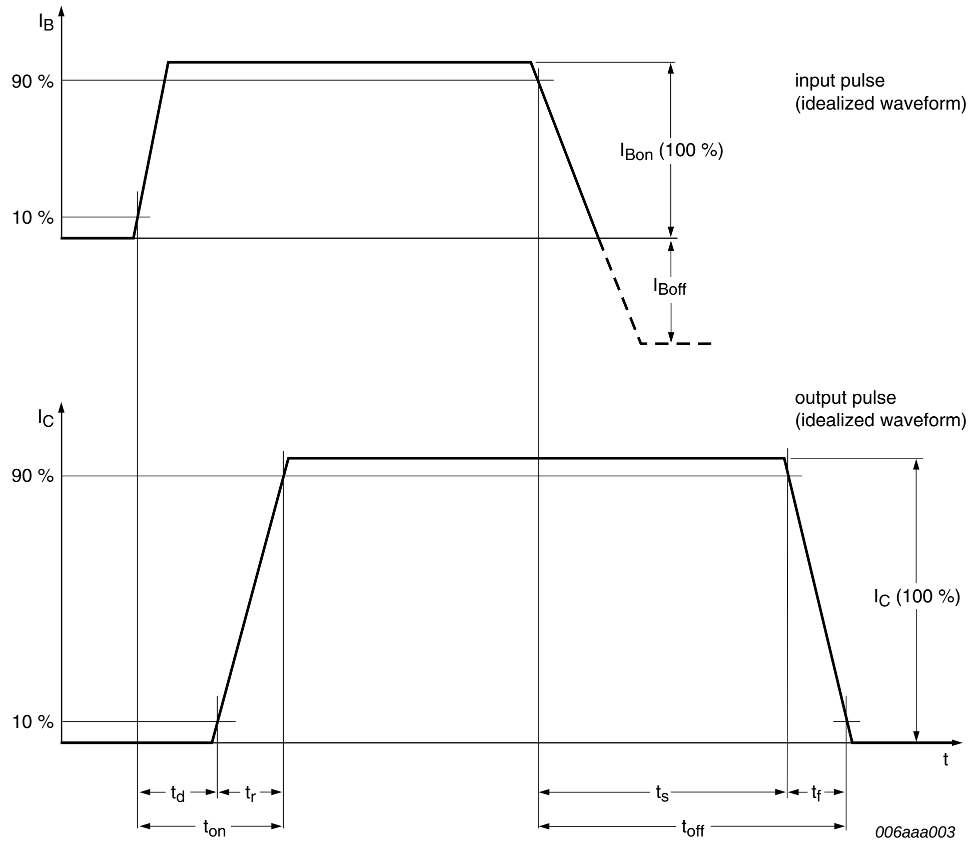
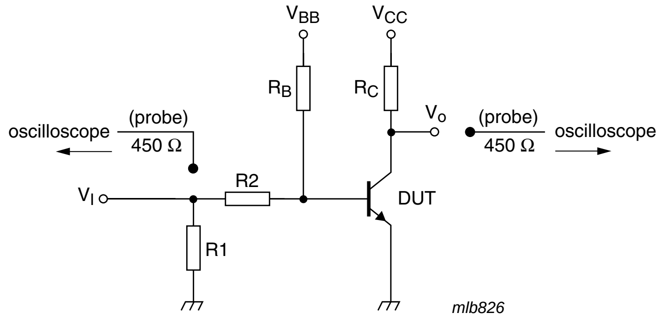



**Fig 14. BISS transistor switching time definition**




$V_{CC}$ = 9 V; $I_C$ = 2 A; $I_{Bon}$ = 0.1 A; $I_{Boff}$ = –0.1 A

**Fig 15. Test circuit for switching times**

## 9. Package outline

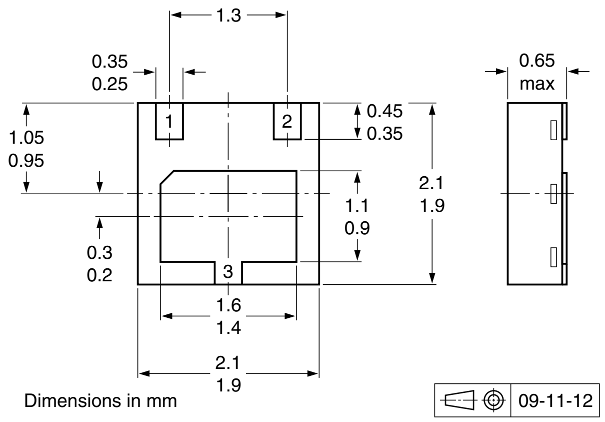



**Fig 16. Package outline SOT1061 (HUSON3)**

## 10. Packing information

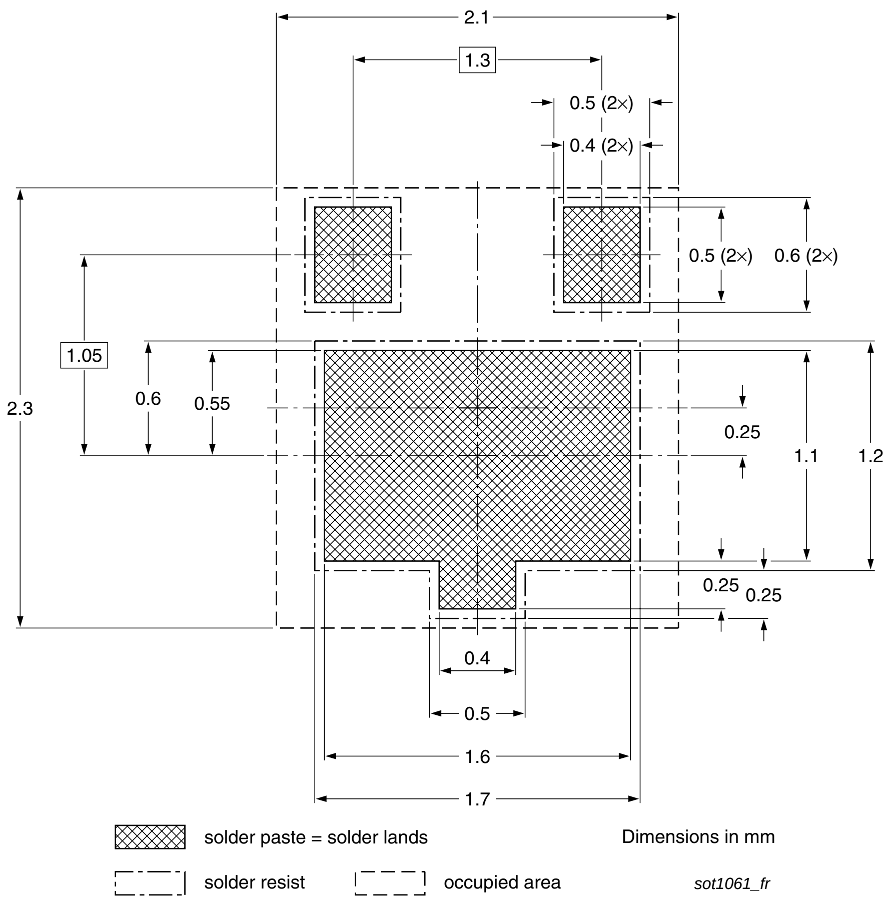
**Table 8. Packing methods**

*The indicated -xxx are the last three digits of the 12NC ordering code.*[1]

| Type number | Package | Description | Packing quantity |
|---|---|---|---|
| | | | 3000 |
| PBSS4330PA | SOT1061 | 4 mm pitch, 8 mm tape and reel | -115 |

[1] For further information and the availability of packing methods, see Section 14.

## 11. Soldering




Reflow soldering is the only recommended soldering method.

**Fig 17. Reflow soldering footprint SOT1061 (HUSON3)**

## 12. Revision history

**Table 9. Revision history**

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---|---|---|---|---|
| PBSS4330PA_1 | 20100419 | Product data sheet | - | - |

# 13. Legal information

## 13.1 Data sheet status

| Document status[1][2] | Product status[3] | Definition |
|---|---|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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## 15. Contents





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